CLAIMS:

1. An electronic package, comprising:

a substrate is a motherboard;

an electronic component in contact with a surface of the substrate such that the electronic component is directly electrically connected to the surface of the substrate;

an interposer mounted to the surface of the substrate such that the interposer surrounds the electronic component without covering the electronic component and is electrically connected to the substrate; and

an over-mold that is in direct contact with an upper surface of the electronic component, wherein the over-mold fills the area between the interposer and the substrate.

2. The electronic package of claim 1, wherein the interposer is organic polymers, fibers and conductors.

3. The electronic package of claim 1, wherein the over-mold is a polymer.

4. The electronic package of claim 1, wherein the over-mold fills an area between the electronic component and the interposer.

5. The electronic package of claim 1, wherein the interposer is mounted to the substrate using solder bumps.

6. The electronic package of claim 1, further comprising solder bumps mounted to an opposing surface of the substrate.

7. An electronic assembly, comprising:

a substrate is a motherboard;

an first electronic component mounted to a surface of the substrate; an interposer in contact with the surface of the substrate such that the interposer surrounds the electronic component without covering the electronic component, the interposer being electrically connected to the substrate, wherein the electronic component is directly electrically connected to the surface of the substrate;

an over-mold that is in direct contact with an upper surface of the electronic component, wherein the over-mold fills the area between the interposer and the substrate; and a second electronic component mounted to the interposer.

8. The electronic assembly of claim 7, wherein the second electronic component is mounted to the interposer using solder bumps.

9. The electronic assembly of claim 7, wherein the second electronic component is electrically connected to the substrate through the interposer.

10. The electronic assembly of claim 7, wherein the second electronic component is a DRAM.

11. A method of fabricating an electronic package, the method comprising:

providing a substrate, wherein the substrate is a motherboard;

attaching an electronic component to a surface of a substrate such that electronic component is in contact with the surface of the substrate and is directly electrically connected to the surface of the substrate;

attaching an interposer to the surface of the substrate such that the interposer surrounds the electronic component without covering the electronic component; and

covering the electronic component with an over-mold such that the over-mold is in direct contact with an upper surface the electronic component, wherein covering the electronic component with an over-mold includes filling in an area between the electronic component and the interposer.

12. The method of claim 11, wherein attaching an interposer to the surface of the substrate includes attaching the interposer to the substrate with solder bumps.

13. The method of claim 11, wherein covering the electronic component with an over-mold includes filling in an area between the substrate and the interposer.

14. A method of fabricating an electronic assembly, the method comprising:

providing a substrate, wherein the substrate is a motherboard;

attaching a first electronic component to a surface of a substrate such that electronic component is in contact with the surface of the substrate and is directly electrically connected to the surface of the substrate;

attaching an interposer to the surface of the substrate such that the interposer surrounds the electronic component;

covering the first electronic component with an over-mold such that the over-mold is in direct contact with an upper surface the electronic component; and

attaching a second electronic component to the interposer, wherein covering the first electronic component with an over-mold includes filling in a first area between a die and the interposer and filling in a second area between the interposer and the substrate.

15. The method of claim 14, wherein attaching a second electronic component to the interposer includes attaching a DRAM to the interposer using solder bumps.